

## 256KB and 512KB BurstRAM™ Secondary Cache Module for Pentium™

The MCM72BB32SG and MCM72BB64SG are designed to provide a burstable, high performance, 256K/512K L2 cache for the Pentium microprocessor. The modules are configured as 32K x 72 and 64K x 72 bits in a 160 pin card edge memory module. Each module uses four of Motorola's MCM67B518 or MCM67B618 BiCMOS BurstRAMs.

Bursts can be initiated with either address status processor ( $\overline{ADSP}$ ) or address status controller ( $\overline{ADSC}$ ). Subsequent burst addresses are generated internal to the BurstRAM by the burst advance ( $\overline{ADV}$ ) input pin.

Write cycles are internally self timed and are initiated by the rising edge of the clock (K) input. Eight write enables are provided for byte write control.

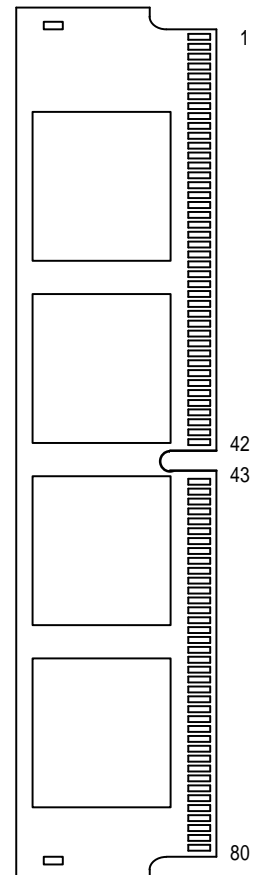
The cache family is designed to interface with popular Pentium cache controllers with on board tag.

PD0 – PD2 are reserved for density identification.

- Pentium-style Burst Counter on Board
- 160 Pin Card Edge Module
- Single 5 V  $\pm$  5% Power Supply
- All Inputs and Outputs are TTL Compatible
- Three State Outputs
- Byte Parity
- Byte Write Capability
- Fast Module Clock Rates: 66 MHz, 60 MHz
- Decoupling Capacitors for each Fast Static RAM
- High Quality Multi-Layer FR4 PWB With Separate Power and Ground Planes
- I/Os are 3.3 V Compatible
- Burndy Connector, Part Number: CELP2X80SC3Z48

**MCM72BB32**  
**MCM72BB64**

160-LEAD  
CARD EDGE  
CASE 1113-01  
TOP VIEW



BurstRAM is a trademark of Motorola.  
Pentium is a trademark of Intel Corp.

REV 1  
5/95

**PIN ASSIGNMENT**  
**160-LEAD CARD EDGE MODULE**  
**TOP VIEW**

PD2	PD1	PD0	Cache Size	Module
V <sub>SS</sub>	V <sub>SS</sub>	NC	256KB	72BB32SG
V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	512KB	72BB64SG

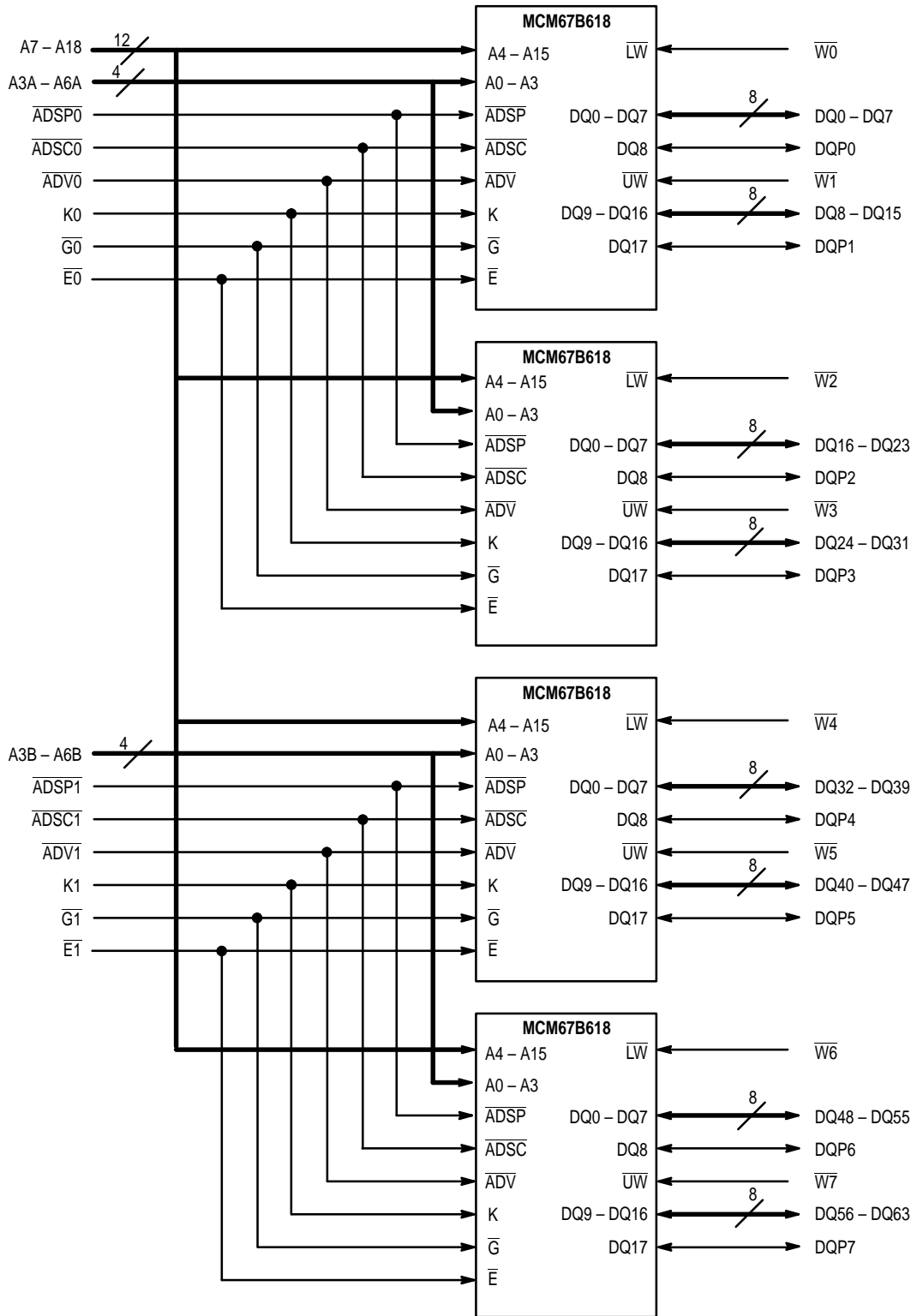
PIN NAMES	
A3 – A18	Address Inputs
K0, K1	Clock
W0 – W7	Byte Write
E0, E1	Module Enable
G0, G1	Module Output Enable
DQ0 – DQ63	Cache Data Input/Output
DQP0 – DQP7	Data Parity Input/Output
ADSC0, ADSC1	Controller Address Status
ADSP0, ADSP1	Processor Address Status
ADV0, ADV1	Burst Advance
PD0 – PD2	Presence Detect
V <sub>CC5</sub>	+ 5 V Power Supply
V <sub>SS</sub>	Ground

\* No Connect for MCM72BB32/MCM72BB64

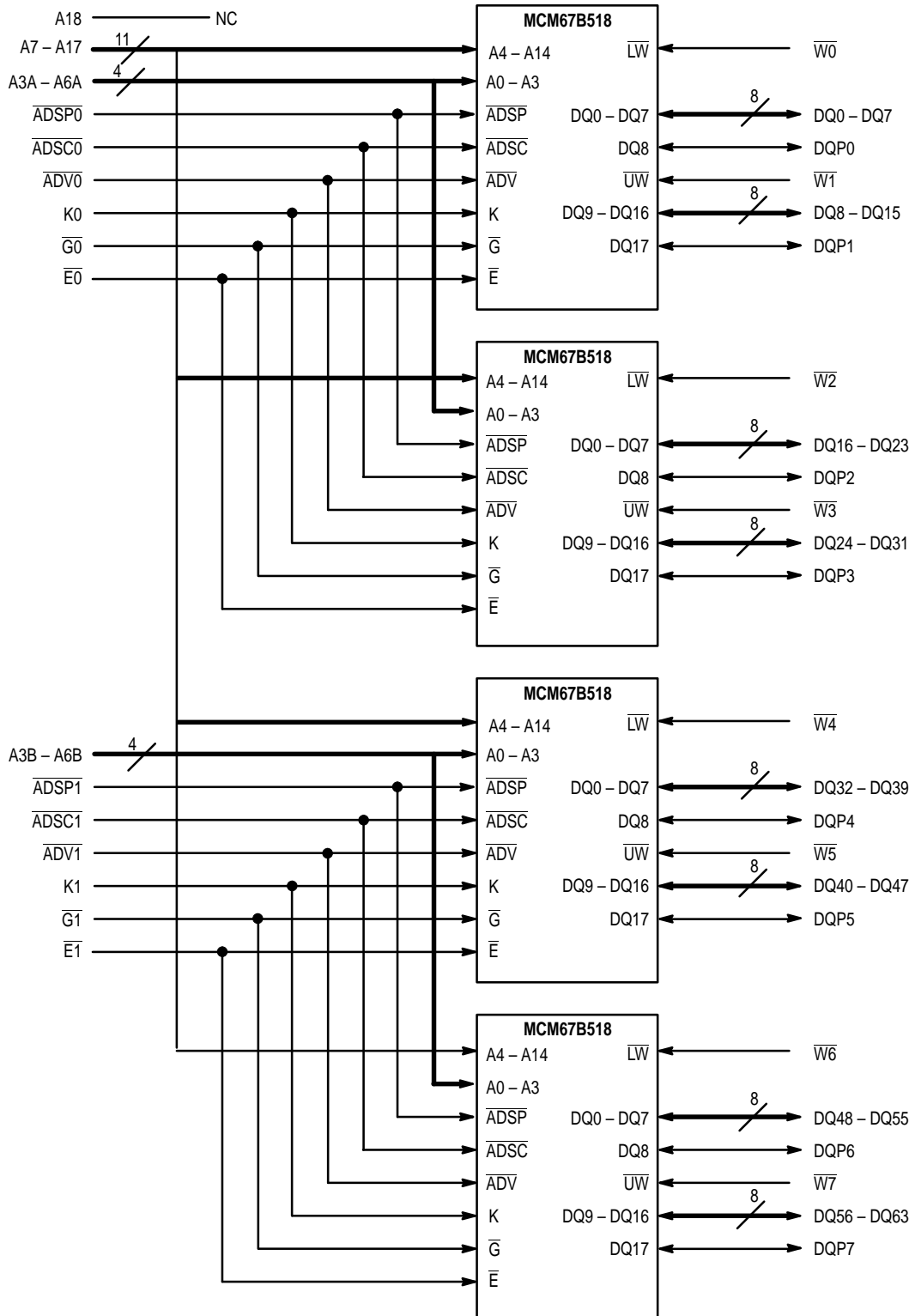
\*\* No Connect for MCM72BB32

V <sub>SS</sub>	81	1	V <sub>SS</sub>
DQ63	82	2	DQ62
V <sub>CC5</sub>	83	3	V <sub>CC3*</sub>
DQ61	84	4	DQ60
V <sub>CC5</sub>	85	5	V <sub>CC3*</sub>
DQ59	86	6	DQ58
DQ57	87	7	DQ56
V <sub>SS</sub>	88	8	V <sub>SS</sub>
DQP7	89	9	DQP6
DQ55	90	10	DQ54
DQ53	91	11	DQ52
DQ51	92	12	DQ50
V <sub>SS</sub>	93	13	V <sub>SS</sub>
DQ49	94	14	DQ48
DQ47	95	15	DQ46
DQ45	96	16	DQ44
DQ43	97	17	DQ42
V <sub>SS</sub>	98	18	V <sub>SS</sub>
DQ41	99	19	DQ40
DQP5	100	20	DQP4
DQ39	101	21	DQ38
DQ37	102	22	DQ36
DQ35	103	23	DQ34
V <sub>SS</sub>	104	24	V <sub>SS</sub>
DQ33	105	25	DQ32
DQ31	106	26	DQ30
DQ29	107	27	DQ28
DQ27	108	28	DQ26
DQ25	109	29	DQ24
V <sub>SS</sub>	110	30	V <sub>SS</sub>
DQP3	111	31	DQP2
DQ23	112	32	DQ22
DQ21	113	33	DQ20
V <sub>CC5</sub>	114	34	V <sub>CC3*</sub>
DQ19	115	35	DQ18
V <sub>SS</sub>	116	36	V <sub>SS</sub>
DQ17	117	37	DQ16
V <sub>CC5</sub>	118	38	V <sub>CC3*</sub>
DQ15	119	39	DQ14
DQ13	120	40	DQ12
V <sub>SS</sub>	121	41	V <sub>SS</sub>
DQ11	122	42	DQ10
V <sub>CC5</sub>	123	43	V <sub>CC3*</sub>
DQ9	124	44	DQ8
DQP1	125	45	DQP0
V <sub>CC5</sub>	126	46	V <sub>CC3*</sub>
DQ7	127	47	DQ6
DQ5	128	48	DQ4
DQ3	129	49	DQ2
DQ1	130	50	DQ0
V <sub>SS</sub>	131	51	V <sub>SS</sub>
A3B	132	52	A3A
A4B	133	53	A4A
A5B	134	54	A5A
A6B	135	55	A6A
A7	136	56	A8
V <sub>SS</sub>	137	57	V <sub>SS</sub>
A9	138	58	A10
A11	139	59	A12
A13	140	60	A14
A15	141	61	A16
A17	142	62	A18**
V <sub>SS</sub>	143	63	V <sub>SS</sub>
*A19	144	64	PD0
PD1	145	65	PD2
K0	146	66	K1
*K2	147	67	K3*
V <sub>SS</sub>	148	68	V <sub>SS</sub>
W7	149	69	W6
W5	150	70	W4
W3	151	71	W2
W1	152	72	W0
V <sub>SS</sub>	153	73	V <sub>SS</sub>
ADSC1	154	74	ADSC0
E1	155	75	E0
ADV1	156	76	ADV0
G1	157	77	G0
V <sub>CC5</sub>	158	78	V <sub>CC3*</sub>
ADSP1	159	79	ADSP0
V <sub>SS</sub>	160	80	V <sub>SS</sub>

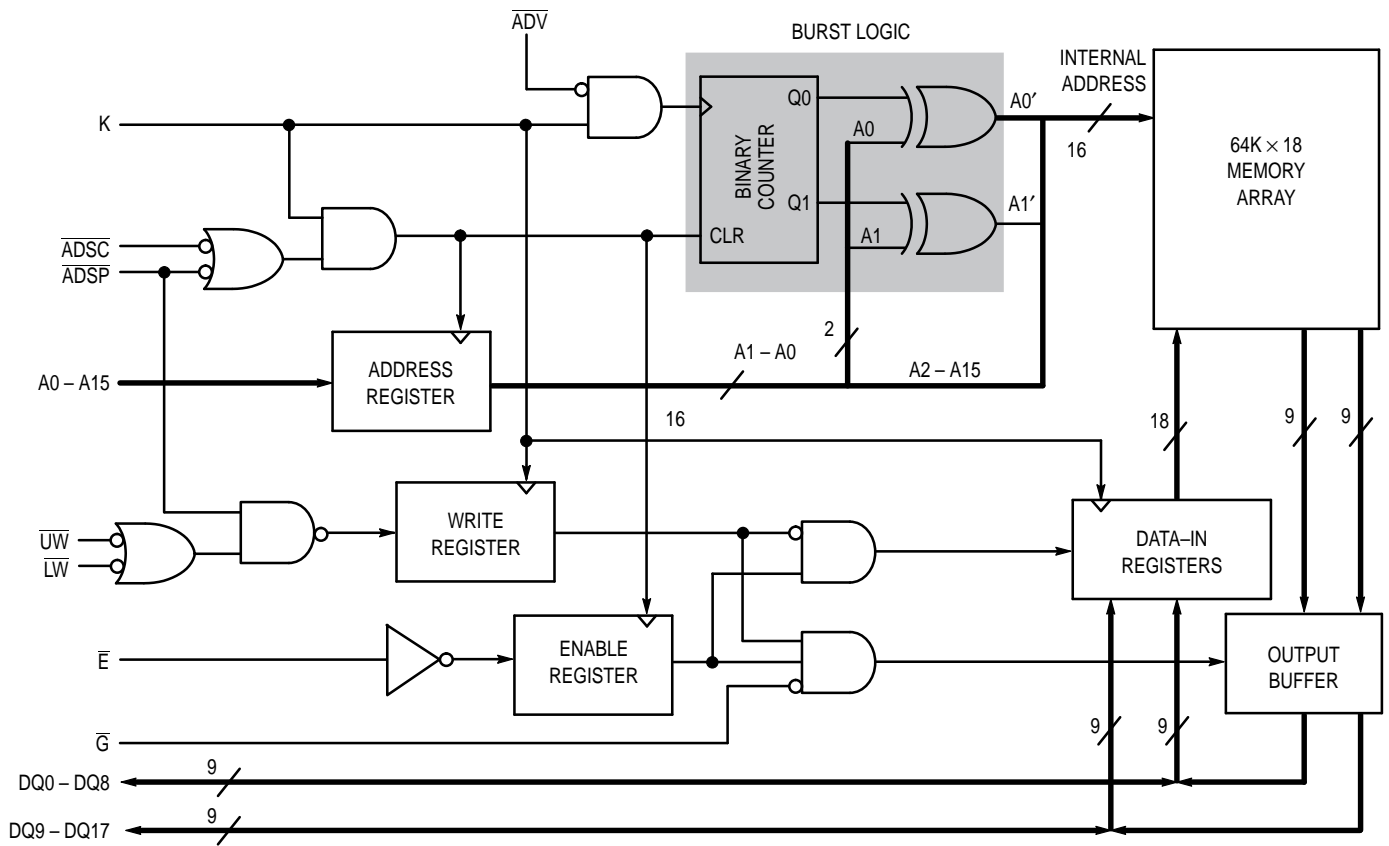
### 64K x 72 BurstRAM MEMORY MODULE BLOCK DIAGRAM



### 32K x 72 BurstRAM MEMORY MODULE BLOCK DIAGRAM



**MCM67B618 BLOCK DIAGRAM** (See Note)



NOTE: All registers are positive-edge triggered. The  $\overline{ADSC}$  or  $\overline{ADSP}$  signals control the duration of the burst and the start of the next burst. When  $\overline{ADSP}$  is sampled low, any ongoing burst is interrupted and a read (independent of  $\overline{W}$  and  $\overline{ADSC}$ ) is performed using the new external address. Alternatively, an  $\overline{ADSP}$ -initiated two cycle WRITE can be performed by asserting  $\overline{ADSP}$  and a valid address on the first cycle, then negating both  $\overline{ADSP}$  and  $\overline{ADSC}$  and asserting  $\overline{LW}$  and/or  $\overline{UW}$  with valid data on the second cycle (see Single Write Cycle in WRITE CYCLES timing diagram). When  $\overline{ADSC}$  is sampled low (and  $\overline{ADSP}$  is sampled high), any ongoing burst is interrupted and a read or write (dependent on  $\overline{W}$ ) is performed using the new external address. Chip enable ( $\overline{E}$ ) is sampled only when a new base address is loaded. After the first cycle of the burst,  $\overline{ADV}$  controls subsequent burst cycles. When  $\overline{ADV}$  is sampled low, the internal address is advanced prior to the operation. When  $\overline{ADV}$  is sampled high, the internal address is not advanced, thus inserting a wait state into the burst sequence accesses. Upon completion of a burst, the address will wrap around to its initial state. See **BURST SEQUENCE TABLE**. Write refers to either or both byte write enables ( $\overline{LW}$ ,  $\overline{UW}$ ).

**BURST SEQUENCE TABLE** (See Note)

External Address	A15 – A2	A1	A0
1st Burst Address	A15 – A2	A1	$\overline{A0}$
2nd Burst Address	A15 – A2	$\overline{A1}$	A0
3rd Burst Address	A15 – A2	$\overline{A1}$	$\overline{A0}$

NOTE: The burst wraps around to its initial state upon completion.

**SYNCHRONOUS TRUTH TABLE** (See Notes 1, 2, and 3)

$\bar{E}$	ADSP	ADSC	ADV	UW or LW	K	Address Used	Operation
H	L	X	X	X	L-H	N/A	Deselected
H	X	L	X	X	L-H	N/A	Deselected
L	L	X	X	X	L-H	External Address	Read Cycle, Begin Burst
L	H	L	X	L	L-H	External Address	Write Cycle, Begin Burst
L	H	L	X	H	L-H	External Address	Read Cycle, Begin Burst
X	H	H	L	L	L-H	Next Address	Write Cycle, Continue Burst
X	H	H	L	H	L-H	Next Address	Read Cycle, Continue Burst
X	H	H	H	L	L-H	Current Address	Write Cycle, Suspend Burst
X	H	H	H	H	L-H	Current Address	Read Cycle, Suspend Burst

NOTES:

1. X means Don't Care.
2. All inputs except  $\bar{G}$  must meet setup and hold times for the low-to-high transition of clock (K).
3. Wait states are inserted by suspending burst.

**ASYNCHRONOUS TRUTH TABLE** (See Notes 1 and 2)

Operation	$\bar{G}$	I/O Status
Read	L	Data Out
Read	H	High-Z
Write	X	High-Z — Data In
Deselected	X	High-Z

NOTES:

1. X means Don't Care.
2. For a write operation following a read operation,  $\bar{G}$  must be high before the input data required setup time and held high through the input data hold time.

**ABSOLUTE MAXIMUM RATINGS** (Voltages Referenced to  $V_{SS} = 0$  V)

Rating	Symbol	Value	Unit
Power Supply Voltage	$V_{CC}$	- 0.5 to + 7.0	V
Voltage Relative to $V_{SS}$ for Any Pin Except $V_{CC}$	$V_{in}, V_{out}$	- 0.5 to $V_{CC} + 0.5$	V
Output Current (per I/O)	$I_{out}$	$\pm 30$	mA
Power Dissipation	$P_D$	6.0	W
Temperature Under Bias	$T_{bias}$	- 10 to + 85	°C
Operating Temperature	$T_A$	0 to + 70	°C
Storage Temperature	$T_{stg}$	- 55 to + 125	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

This device contains circuitry that will ensure the output devices are in High-Z at power up.

## DC OPERATING CONDITIONS AND CHARACTERISTICS

( $V_{CC} = 5.0 \text{ V} \pm 5\%$ ,  $T_A = 0 \text{ to } +70^\circ\text{C}$ , Unless Otherwise Noted)

### RECOMMENDED OPERATING CONDITIONS (Voltages referenced to $V_{SS} = 0 \text{ V}$ )

Parameter	Symbol	Min	Max	Unit
Supply Voltage (Operating Voltage Range)	$V_{CC}$	4.75	5.25	V
Input High Voltage	$V_{IH}$	2.2	$V_{CC} + 0.3^{**}$	V
Input Low Voltage	$V_{IL}$	-0.5*	0.8	V

\*  $V_{IL}(\text{min}) = -0.5 \text{ V dc}$ ;  $V_{IL}(\text{min}) = -2.0 \text{ V ac}$  (pulse width  $\leq 20.0 \text{ ns}$ ) for  $I \leq 20.0 \text{ mA}$ .

\*\*  $V_{IH}(\text{max}) = V_{CC} + 0.3 \text{ V dc}$ ;  $V_{IH}(\text{max}) = V_{CC} + 2.0 \text{ V ac}$  (pulse width  $\leq 20.0 \text{ ns}$ ) for  $I \leq 20.0 \text{ mA}$ .

### DC CHARACTERISTICS AND SUPPLY CURRENTS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, $V_{in} = 0 \text{ to } V_{CC}$ )	$I_{kg}(I)$	—	$\pm 1.0$	$\mu\text{A}$
Output Leakage Current ( $\bar{G} = V_{IH}$ )	$I_{kg}(O)$	—	$\pm 1.0$	$\mu\text{A}$
AC Supply Current ( $\bar{G} = V_{IH}$ , $\bar{E} = V_{IL}$ , $I_{out} = 0 \text{ mA}$ , All Inputs = $V_{IL}$ or $V_{IH}$ , $V_{IL} = 0.0 \text{ V}$ and $V_{IH} \geq 3.0 \text{ V}$ , Cycle Time $\geq t_{KHKH} \text{ min}$ )	$I_{CCA66}$ $I_{CCA60}$	—	1100 1060	mA
AC Standby Current ( $\bar{E} = V_{IH}$ , $I_{out} = 0 \text{ mA}$ , All Inputs = $V_{IL}$ and $V_{IH}$ , $V_{IL} = 0.0 \text{ V}$ and $V_{IH} \geq 3.0 \text{ V}$ , Cycle Time $\geq t_{KHKH} \text{ min}$ )	$I_{SB1}$	—	380	mA
Output Low Voltage ( $I_{OL} = +8.0 \text{ mA}$ )	$V_{OL}$	—	0.4	V
Output High Voltage ( $I_{OH} = -4.0 \text{ mA}$ )	$V_{OH}$	2.4	3.3	V

NOTE: Good decoupling of the local power supply should always be used. DC characteristics are guaranteed for all possible Pentium bus cycles.

### CAPACITANCE (f = 1.0 MHz, dV = 3.0 V, $T_A = 25^\circ\text{C}$ , Periodically Sampled Rather Than 100% Tested)

Parameter	Symbol	Max	Unit
Input Capacitance (A7 – A18)	$C_{in}$	20	pF
Input Capacitance (A3x – A6x, ADSPx, ADSCx, ADVx, Kx, Gx, Ex, Wx)	$C_{in}$	10	pF
Input/Output Capacitance (DQ0 – DQ63, DQP0 – DQP7)	$C_{I/O}$	8	pF

## AC OPERATING CONDITIONS AND CHARACTERISTICS

( $V_{CC} = 5.0\text{ V} \pm 5\%$ ,  $T_A = 0\text{ to } +70^\circ\text{C}$ , Unless Otherwise Noted)

Input Timing Measurement Reference Level ..... 1.5 V  
 Input Pulse Levels ..... 0 to 3.0 V  
 Input Rise/Fall Time ..... 3 ns

Output Timing Reference Level ..... 1.5 V  
 Output Load ..... See Figure 1A Unless Otherwise Noted

### READ/WRITE CYCLE TIMING (See Notes 1, 2, and 3) ( $\overline{Wx}$ refers to any or all byte write enables)

Parameter	Symbol	MCM72BB64SG66		MCM72BB64SG60		Unit	Notes	
		Min	Max	Min	Max			
Cycle Time	$t_{KHKH}$	15	—	16.7	—	ns		
Clock Access Time	$t_{KHQV}$	—	9	—	10	ns	4	
Output Enable to Output Valid	$t_{GLQV}$	—	5	—	5	ns		
Clock High to Output Active	$t_{KHQX1}$	6	—	6	—	ns		
Clock High to Output Change	$t_{KHQX2}$	3	—	3	—	ns		
Output Enable to Output Active	$t_{GLQX}$	0	—	0	—	ns		
Output Disable to Q High-Z	$t_{GHQZ}$	2	6	2	6	ns	5	
Clock High to Q High-Z	$t_{KHQZ}$	—	6	—	6	ns		
Clock High Pulse Width	$t_{KHKL}$	5	—	5	—	ns		
Clock Low Pulse Width	$t_{KLKH}$	5	—	5	—	ns		
Setup Times:	Address Address Status Data In Write Address Advance Chip Enable	$t_{AVKH}$ $t_{ADSVKH}$ $t_{DVKH}$ $t_{VVKH}$ $t_{ADVVKH}$ $t_{EVKH}$	2.5	—	2.5	—	ns	6
Hold Times:	Address Address Status Data In Write Address Advance Chip Enable	$t_{KHAX}$ $t_{KHADSX}$ $t_{KHDX}$ $t_{KHWX}$ $t_{KHADVX}$ $t_{KHEX}$	0.5	—	0.5	—	ns	6

#### NOTES:

1. A read cycle is defined by  $\overline{UW}$  and  $\overline{LW}$  high or  $\overline{ADSP}$  low for the setup and hold times. A write cycle is defined by  $\overline{LW}$  or  $\overline{UW}$  low and  $\overline{ADSP}$  high for the setup and hold times.
2. All read and write cycle timings are referenced from K or  $\overline{G}$ .
3.  $\overline{G}$  is a don't care when  $\overline{UW}$  or  $\overline{LW}$  is sampled low.
4. Maximum access times are guaranteed for all possible Pentium external bus cycles.
5. Transition is measured  $\pm 500\text{ mV}$  from steady-state voltage with load of Figure 1B. This parameter is sampled rather than 100% tested. At any given voltage and temperature,  $t_{KHQZ}$  max is less than  $t_{KHQZ1}$  min for a given device and from device to device.
6. This is a synchronous device. All addresses must meet the specified setup and hold times for **ALL** rising edges of K whenever  $\overline{ADSP}$  or  $\overline{ADSC}$  is low, and the chip is selected. All other synchronous inputs must meet the specified setup and hold times for **ALL** rising edges of K when the chip is enabled. Chip enable must be valid at each rising edge of clock for the device (when  $\overline{ADSP}$  or  $\overline{ADSC}$  is low) to remain enabled.

### AC TEST LOADS

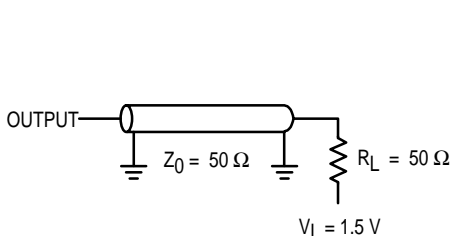


Figure 1A

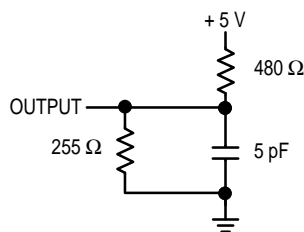
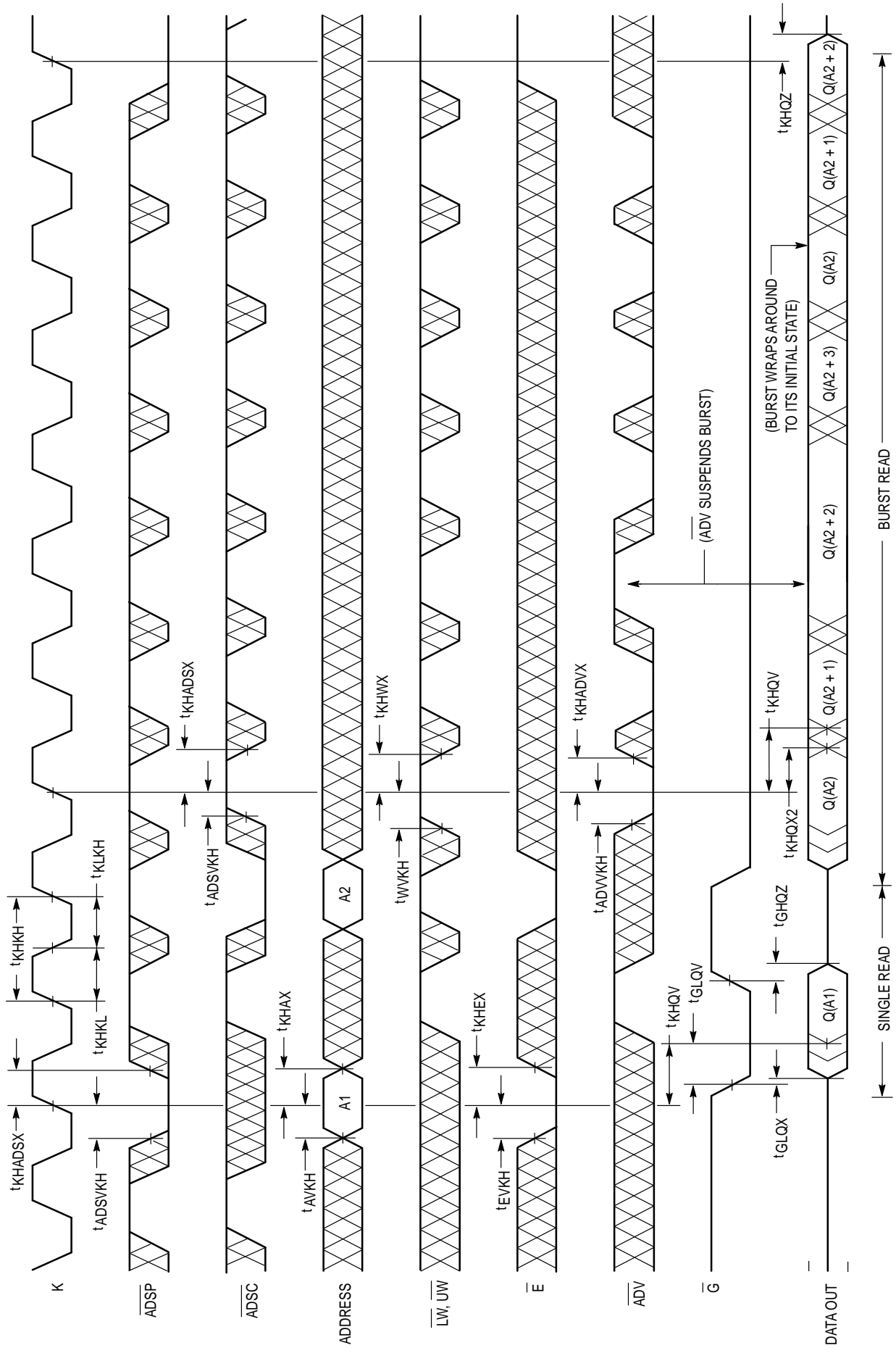


Figure 1B

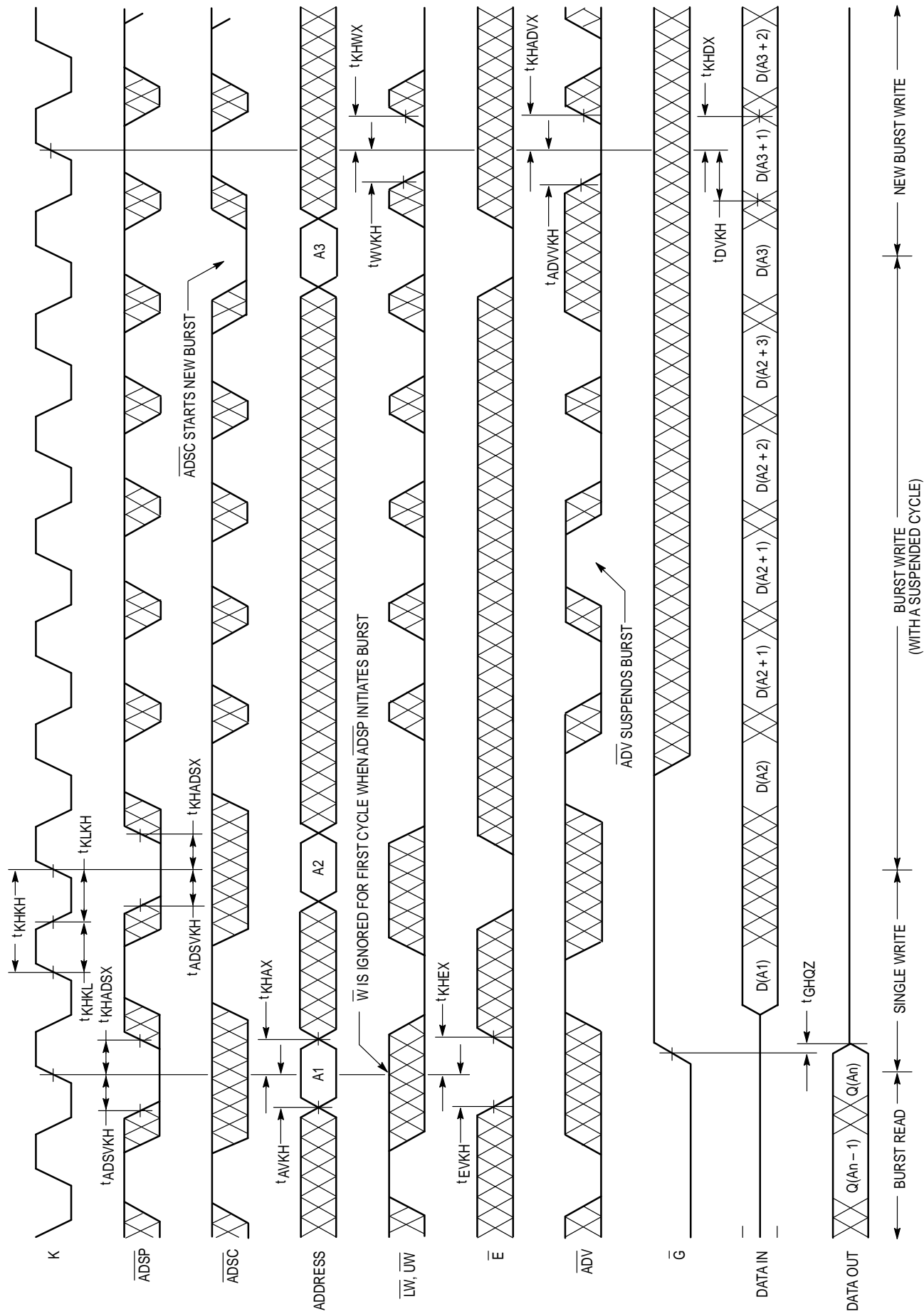


# READ CYCLES

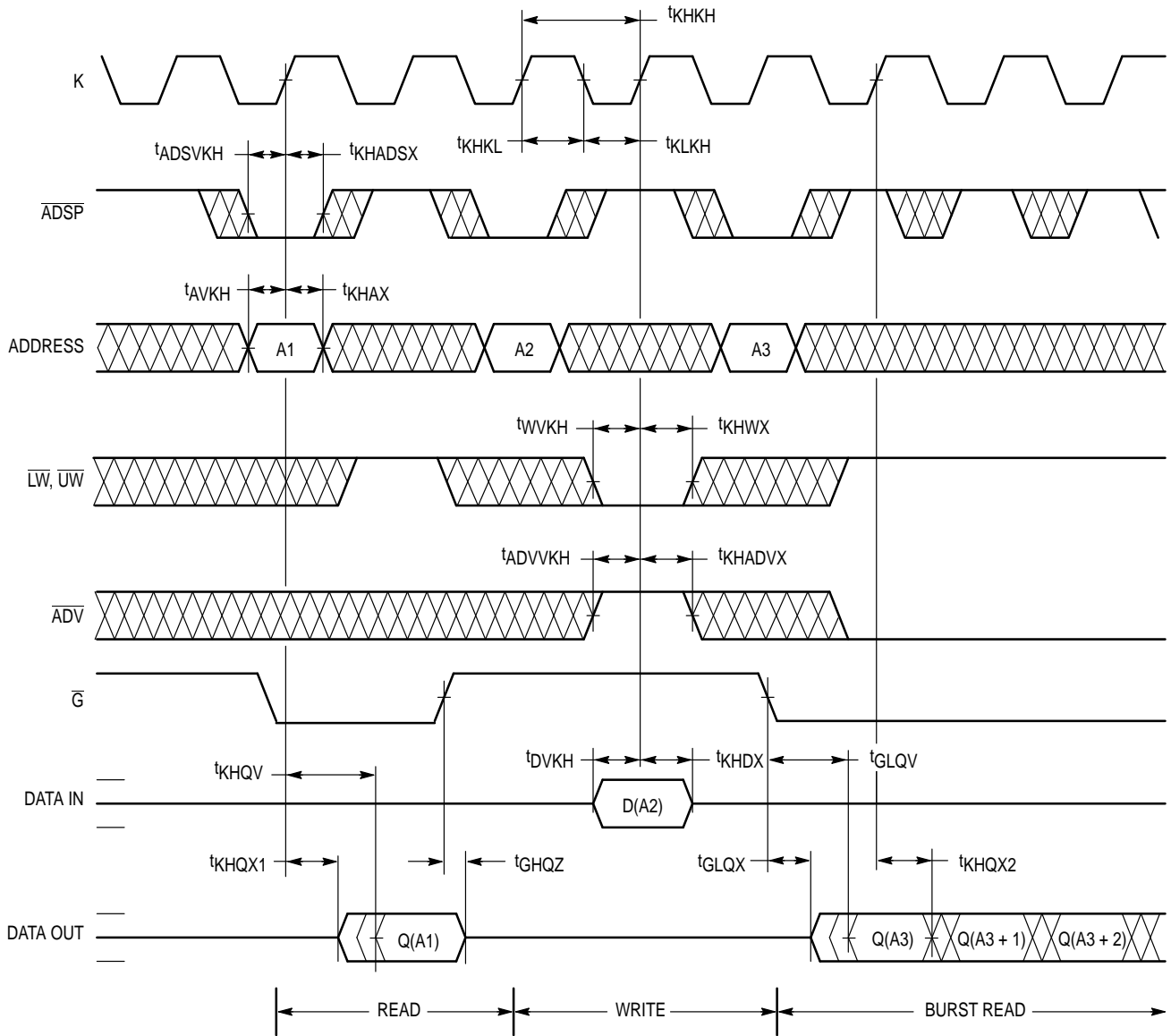


NOTE: Q(A2) represents the first output data from the base address A2; Q(A2 + 1) represents the next output data in the burst sequence with A2 as the base address.

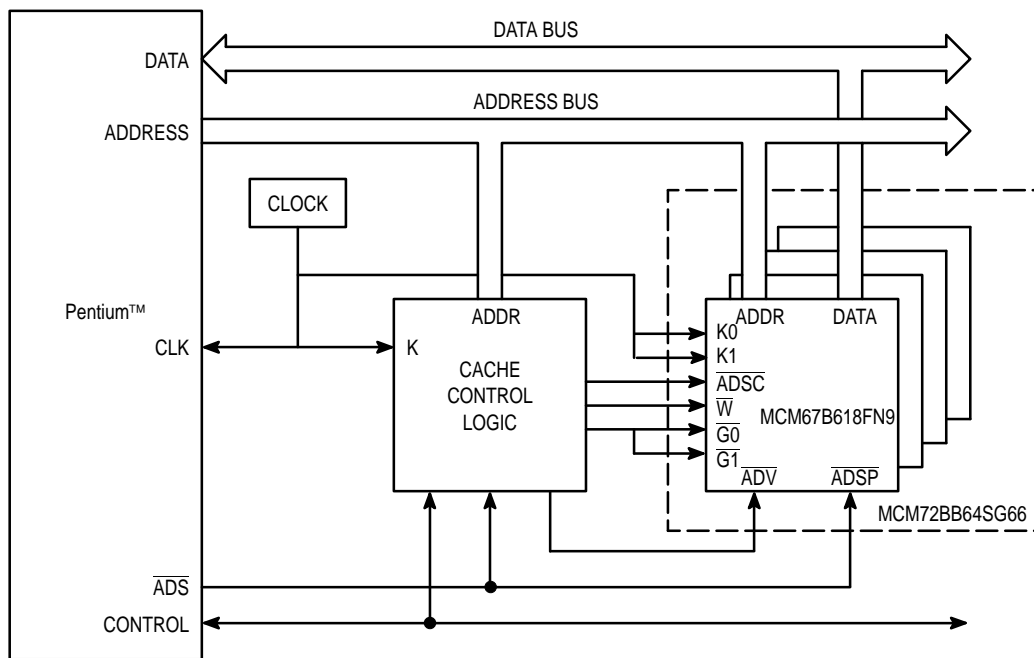
## WRITE CYCLES



### COMBINATION READ/WRITE CYCLE



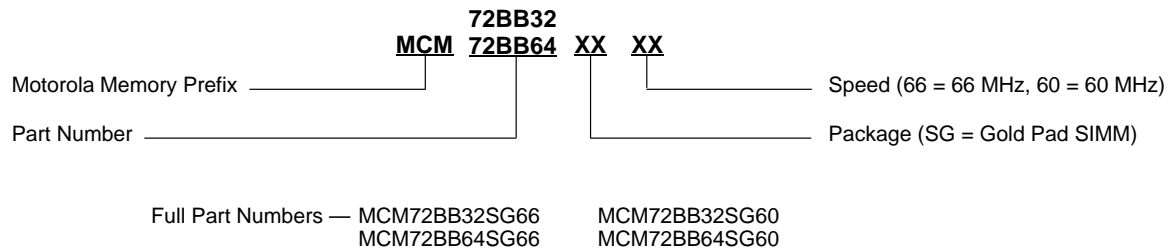
## APPLICATION EXAMPLE



512K Byte Burstable, Secondary Cache  
Using MCM72BB64SG66 with a 66 MHz Pentium

Figure 2

## ORDERING INFORMATION (Order by Full Part Number)

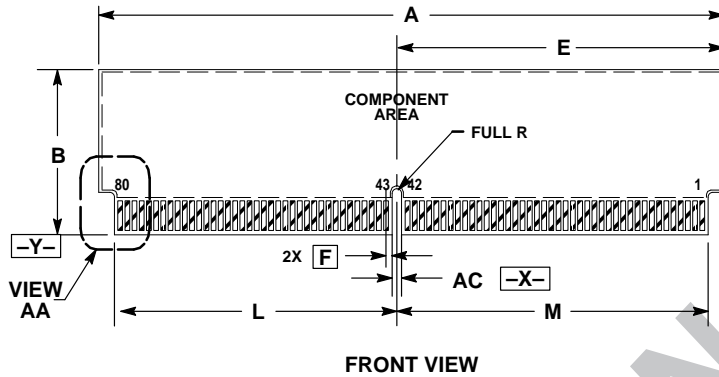


# PACKAGE DIMENSIONS

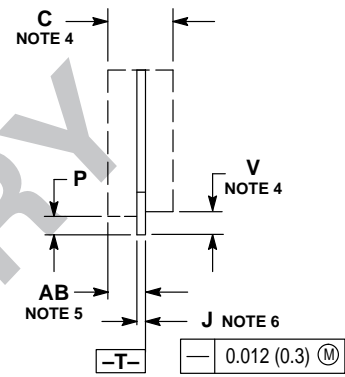
## CARD EDGE MODULE

160-LEAD

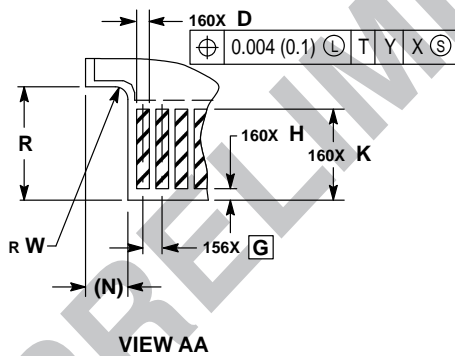
CASE 1113-01



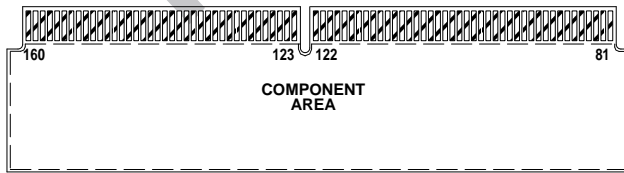
FRONT VIEW



SIDE VIEW



VIEW AA




BACK VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
4. DIMENSIONS C AND V DEFINE A DOUBLE-SIDED MODULE.
5. DIMENSION AB DEFINES OPTIONAL SINGLE-SIDED MODULE.
6. STRAIGHTNESS CALLOUT APPLIES TO TAB AREA ONLY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	4.330	4.350	109.98	110.49
B	1.290	1.310	32.77	33.27
C	—	0.454	—	11.53
D	0.033	0.037	0.84	0.94
E	2.265	2.275	57.53	57.79
F	—	0.075 BSC	—	1.91 BSC
G	—	0.050 BSC	—	1.27 BSC
H	—	0.030	—	0.51
J	0.055	0.069	1.40	1.75
K	0.210	—	5.33	—
L	1.955	1.965	49.66	49.91
M	2.155	2.165	54.74	54.99
N	—	0.110 REF	—	2.79 REF
P	0.125	—	3.18	—
R	0.285	0.305	7.24	7.75
V	0.157	—	3.99	—
W	0.040	0.060	1.02	1.52
AB	—	0.262	—	6.66
AC	0.072	0.076	1.83	1.93

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and  are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

**Literature Distribution Centers:**

USA/EUROPE: Motorola Literature Distribution; P.O. Box 20912; Phoenix, Arizona 85036.

JAPAN: Nippon Motorola Ltd.; 4-32-1, Nishi-Gotanda, Shinagawa-ku, Tokyo 141, Japan.

ASIA PACIFIC: Motorola Semiconductors H.K. Ltd.; Silicon Harbour Center, No. 2 Dai King Street, Tai Po Industrial Estate, Tai Po, N.T., Hong Kong.



MCM72BB32/D

